

## Glass Passivated Bridge Rectifiers 玻璃钝化整流桥

**Reverse Voltage - 50 to 1000 Volts**  
反向电压 50-1000V  
**Forward Current - 35 Amperes**  
正向电流 35A

### Features 特征

- Glass passivated chip 玻璃钝化芯片
- Low forward voltage drop 正向压降低
- Ideal for printed circuit board 适用于印刷电路板中
- High surge current capability 高的浪涌能力

### Mechanical Data 外观信息

- Polarity: Symbol marked on body 极性: 标志在产品的本体上
- Mounting position: Any 安装位置: 任何位置

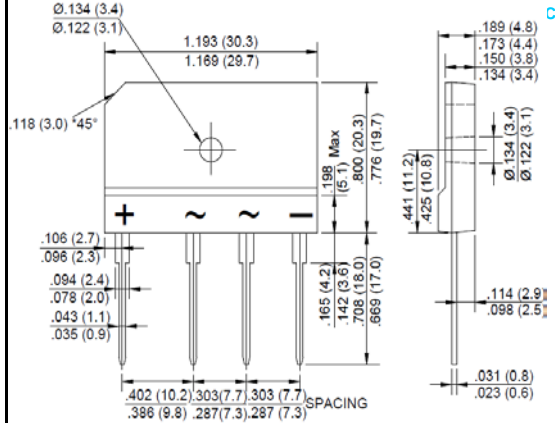
### Applications 应用

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.  
一般应用于交流/直流桥式全波整流, 如: 开关电源, 照明镇流器、适配器等。

GBJ



RoHS  
COMPLIANT



## Maximum Ratings and Electrical Characteristics 最大额定值及电气特性

Rating at 25°C ambient temperature unless otherwise specified. 环境温度25°C, 除非特别说明。  
Single phase, half wave, 60Hz, resistive or inductive load. 单相半波, 60Hz, 阻性或感性负载。  
For capacitive load, derate current by 20%. 对于电容性负载, 降低20%的额定电流。

Characteristics 特性	Symbol 符号	GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	Unit 单位	
Maximum Repetitive Peak Reverse Voltage 最大重复峰值反向电压	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V	
Maximum RMS Voltage 最大有效反向电压	V <sub>RMS</sub>	35	70	140	280	420	560	700	V	
Maximum DC Blocking Voltage 最大直流阻断电压	V <sub>DC</sub>	50	100	200	400	600	800	1000	V	
Maximum Average Forward Rectified Current (with heatsink Note 2) 最大正向平均整流电流 @ T <sub>c</sub> =100°C (without heatsink)	I <sub(av)< sub=""></sub(av)<>	35.0							5.0	A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method) 8.3mS单一正弦半波叠加在额定负载上的浪涌能力 (JEDEC方法)	I <sub>FSM</sub>	400								A
I <sup>2</sup> t Rating for Fusing (t<8.3mS) 熔断额定值 (t<8.3mS)	I <sup>2</sup> t	664								A <sup>2</sup> s
Peak Forward Voltage per Diode at 17.5A DC 单个二极管在17.5A电流下的正向峰值电压	V <sub>F</sub>	1.1								V
Maximum DC Reverse Current at Rated @ T <sub>J</sub> =25°C DC Blocking Voltage per Diode @ T <sub>J</sub> =125°C 单个二极管在额定直流电压下的最大反向直流电流	I <sub>R</sub>	10.0							500	μA
Typical Junction Capacitance per Diode (Note1) 典型结电容 (备注1)	C <sub>J</sub>	85								pF
Typical Thermal Resistance to Ambient (Note2) 结到环境的典型热阻值 (备注2)	R <sub>θJA</sub>	4.0								°C/W
Typical Thermal Resistance to case (Note2) 结到壳的典型热阻值 (备注2)	R <sub>θJC</sub>	0.6								
Typical Thermal Resistance to lead (Note2) 结到引线的典型热阻值 (备注2)	R <sub>θJL</sub>	1.5								
Operating Junction Temperature Range 结温工作范围	T <sub>J</sub>	-55 to +150								°C
Storage Temperature Range 储存温度范围	T <sub>STG</sub>	-55 to +150								°C

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC. 在 1.0MHz 下和反向电压为 4.0V DC 下测试。

2. Device mounted on 300mm\*300mm\*1.6mm Cu plate heatsink. 安装在 300mm\*300mm\*1.6mm Cu 的散热片上。

3. The typical data above is for reference only (典型值仅供参考)。

Fig. 1 - Forward Current Derating Curve

图1 正向电流降额曲线

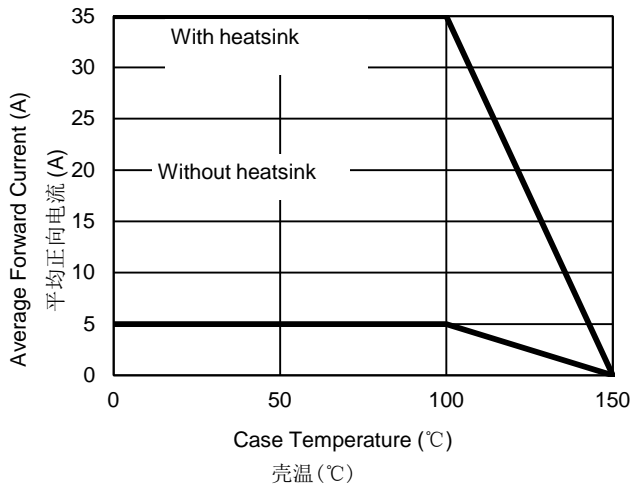


Fig. 2 - Maximum Non-Repetitive Surge Current

图2 最大不重复正向浪涌曲线

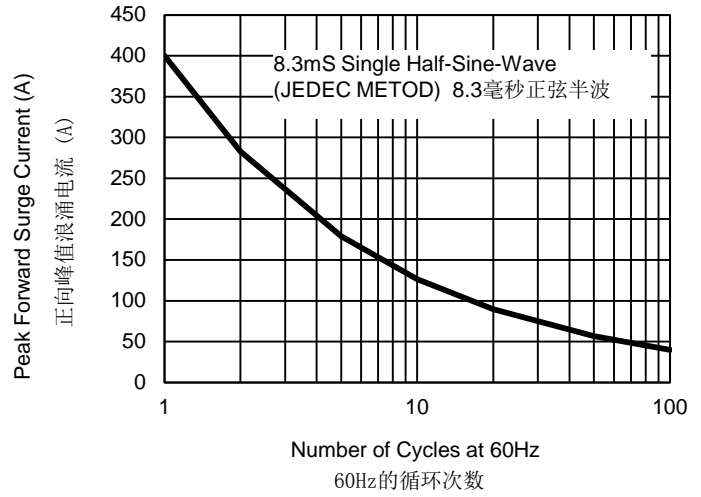


Fig. 3 - Typical Reverse Characteristics

图3 典型的反向特性

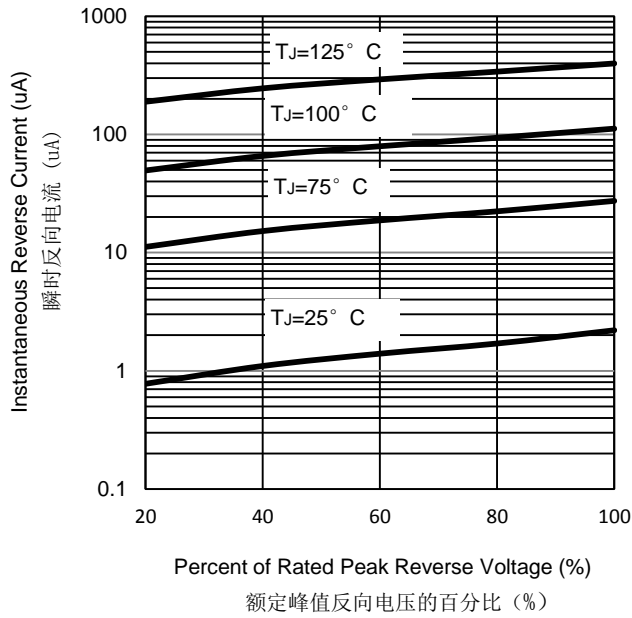
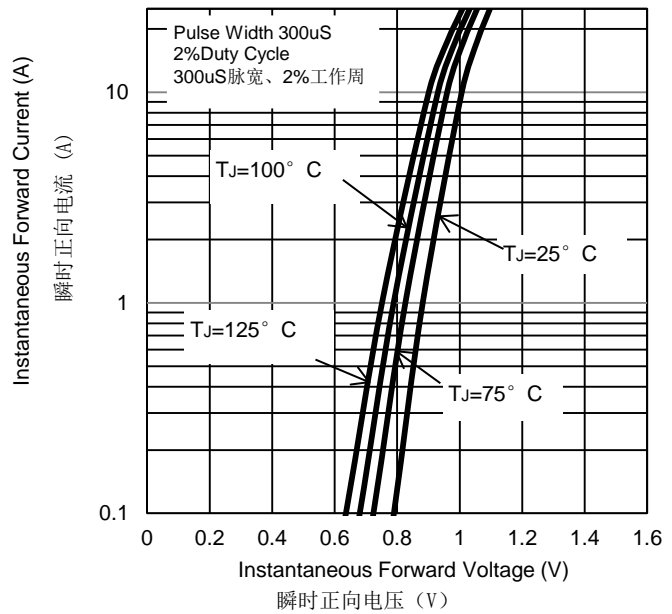


Fig. 4 - Typical Forward Characteristics

图4 典型的正向特性





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